

# FDMS030N06B

## N-Channel PowerTrench® MOSFET

60 V, 100 A, 3 mΩ

### Features

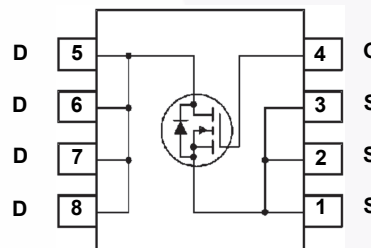
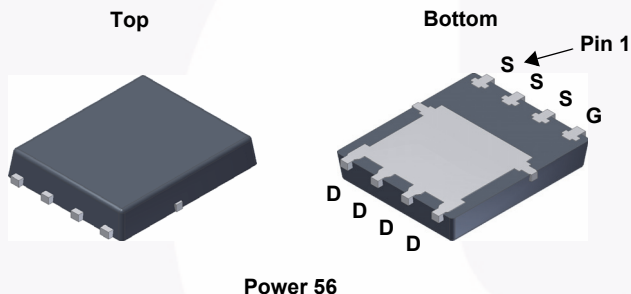
- $R_{DS(on)} = 2.4 \text{ m}\Omega$  (Typ.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 50 \text{ A}$
- Advanced Package and Silicon Combination for Low  $R_{DS(on)}$  and High Efficiency
- Fast Switching Speed
- 100% UIL Tested
- RoHS Compliant

### Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advance PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

### Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor drives and Uninterruptible Power Supplies
- Renewable system



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter		FDMS030N06B	Unit
$V_{DSS}$	Drain to Source Voltage		60	V
$V_{GSS}$	Gate to Source Voltage		$\pm 20$	V
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ ) (Note 1)	100	A
		- Continuous ( $T_A = 25^\circ\text{C}$ ) (Note 2a)	22.1	
$I_{DM}$	Drain Current	- Pulsed (Note 3)	400	A
$E_{AS}$	Single Pulsed Avalanche Energy (Note 4)		248	mJ
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	104	W
		( $T_A = 25^\circ\text{C}$ ) (Note 2a)	2.5	
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter		FDMS030N06B	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.		1.2	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. (Note 2a)		50	

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS030N06B	FDMS030N06B	Power 56	13 "	12 mm	3000 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\ \mu\text{A}$ , $V_{GS} = 0\text{V}$	60	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	0.03	-	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 48\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\ \mu\text{A}$	2.5	3.3	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}$ , $I_D = 50\text{A}$	-	2.4	3.0	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{V}$ , $I_D = 50\text{A}$	-	119	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 30\text{V}$ , $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	5685	7560	pF
$C_{oss}$	Output Capacitance		-	1720	2290	pF
$C_{rss}$	Reverse Transfer Capacitance		-	59	-	pF
$C_{oss(er)}$	Energy Related Output Capacitance	$V_{DS} = 30\text{V}$ , $V_{GS} = 0\text{V}$	-	2504	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 30\text{V}$ , $I_D = 50\text{A}$ $V_{GS} = 0\text{V}$ to $10\text{V}$	-	75	-	nC
$Q_{gs}$	Gate to Source Gate Charge		-	30	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	14	-	nC
$V_{plateau}$	Gate Plateau Voltage		(Note 5)	5.4	-	V
$Q_{sync}$	Total Gate Charge Sync.	$V_{DS} = 0\text{V}$ , $I_D = 50\text{A}$	-	66.2	-	nC
$Q_{oss}$	Output Charge	$V_{DS} = 30\text{V}$ , $V_{GS} = 0\text{V}$	-	174	-	nC
ESR	Equivalent Series Resistance	$f = 1\text{MHz}$	-	1.05	-	$\Omega$

### Switching Characteristics

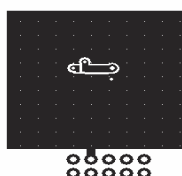
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30\text{V}$ , $I_D = 50\text{A}$ $V_{GS} = 10\text{V}$ , $R_G = 4.7\ \Omega$	-	39	88	ns
$t_r$	Turn-On Rise Time		-	20	50	ns
$t_{d(off)}$	Turn-Off Delay Time		-	52	114	ns
$t_f$	Turn-Off Fall Time		(Note 5)	16	42	ns

### Drain-Source Diode Characteristics

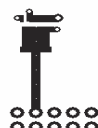
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	100	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	400	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 50 A	-	-	1.25	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 50 A	-	71	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di <sub>F</sub> /dt = 100 A/μs	-	85	-	nC

#### Notes:

1. Silicon limited  $I_D$  rating = 147 A.
2.  $R_{\theta JA}$  is determined with the device mounted on a  $1\text{in}^2$  pad 2 oz copper pad on a  $1.5 \times 1.5\text{in.}$  board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a.  $50\ ^\circ\text{C}/\text{W}$  when mounted on a  $1\text{in}^2$  pad of 2 oz copper.



b.  $125\ ^\circ\text{C}/\text{W}$  when mounted on a minimum pad of 2 oz copper.

3. Repetitive rating: pulse-width limited by maximum junction temperature.
4.  $L = 0.3\text{mH}$ ,  $I_{AS} = 40.7\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $V_{GS} = 10\text{V}$ , starting  $T_J = 25^\circ\text{C}$ .
5. Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

Figure 1. On-Region Characteristics

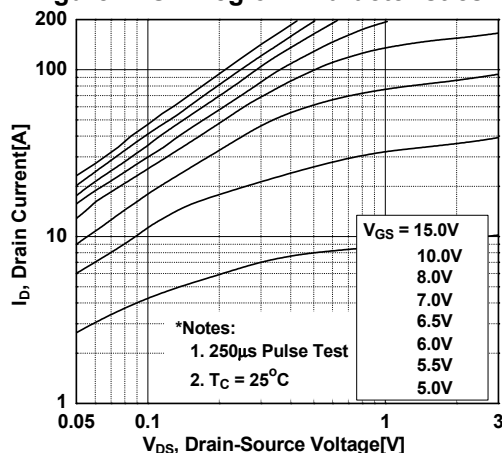


Figure 2. Transfer Characteristics

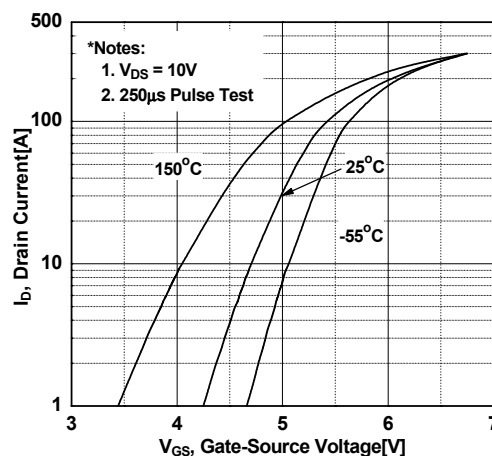


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

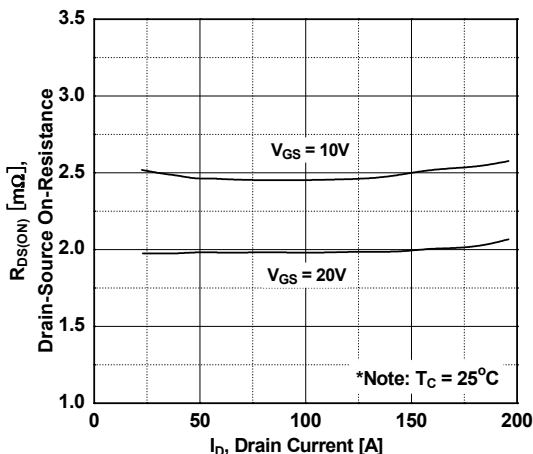


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

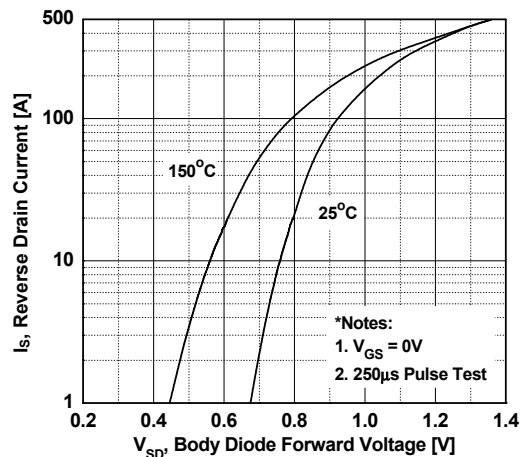


Figure 5. Capacitance Characteristics

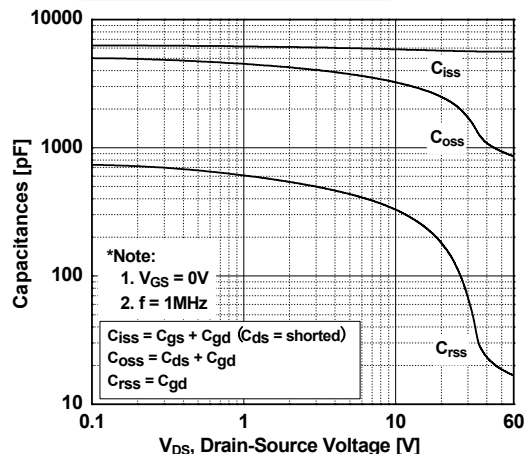
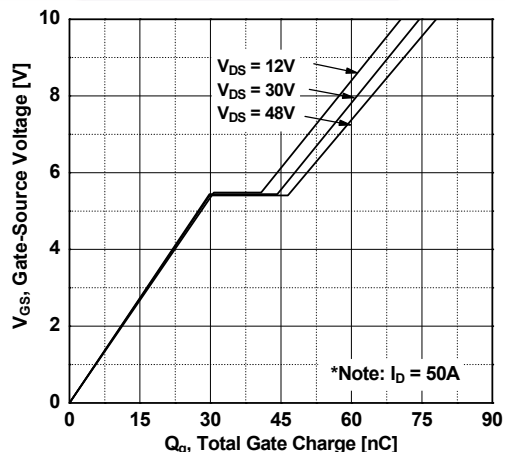


Figure 6. Gate Charge Characteristics



## Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

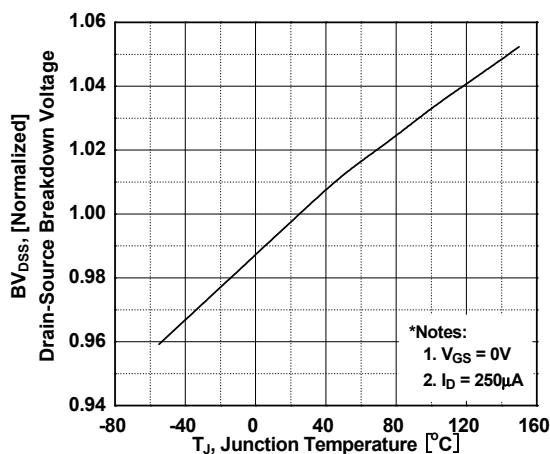


Figure 8. On-Resistance Variation vs. Temperature

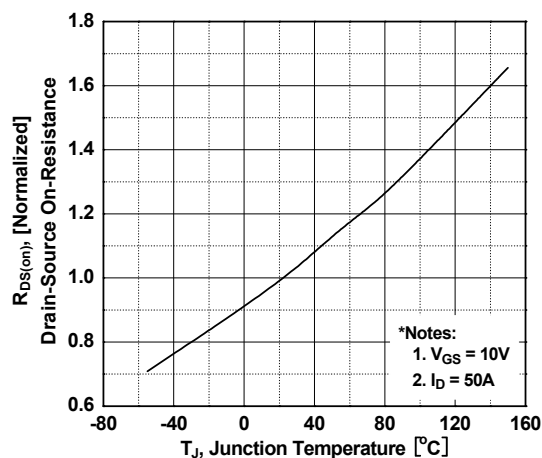


Figure 9. Maximum Safe Operating Area

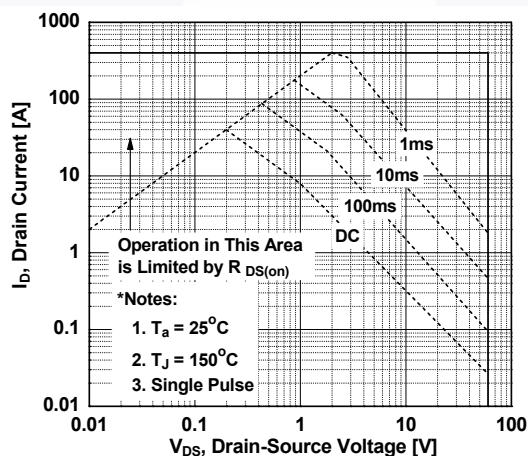


Figure 10. Maximum Drain Current vs. Case Temperature

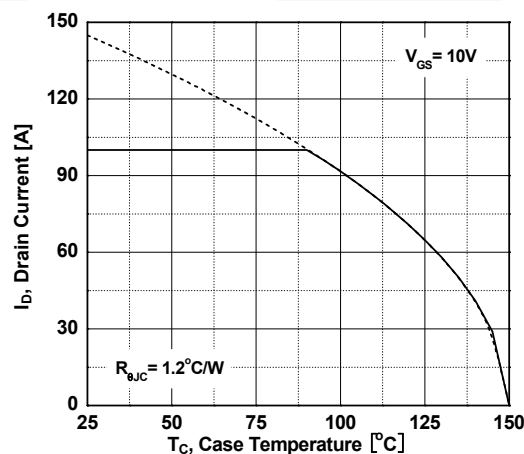


Figure 11. E\_oss vs. Drain to Source Voltage

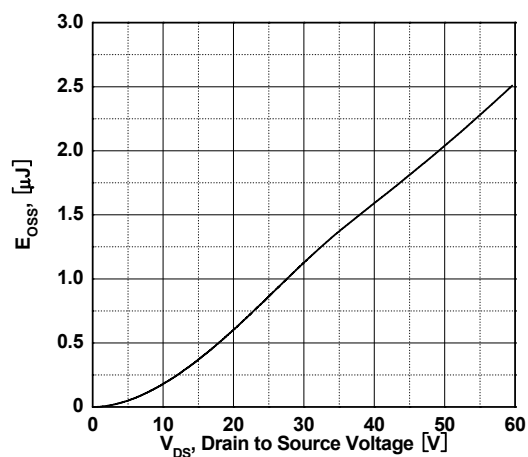
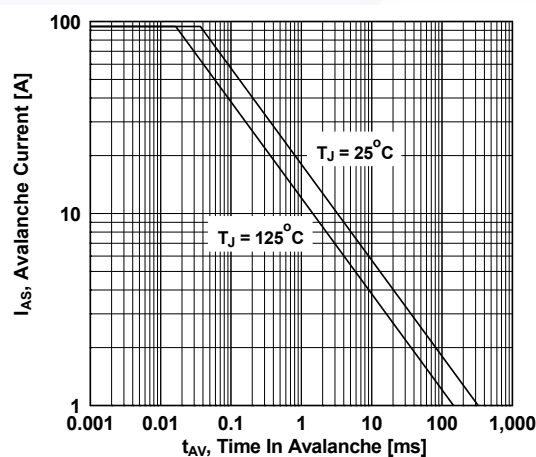


Figure 12. Unclamped Inductive Switching Capability



## Typical Performance Characteristics (Continued)

Figure 13. Transient Thermal Response Curve

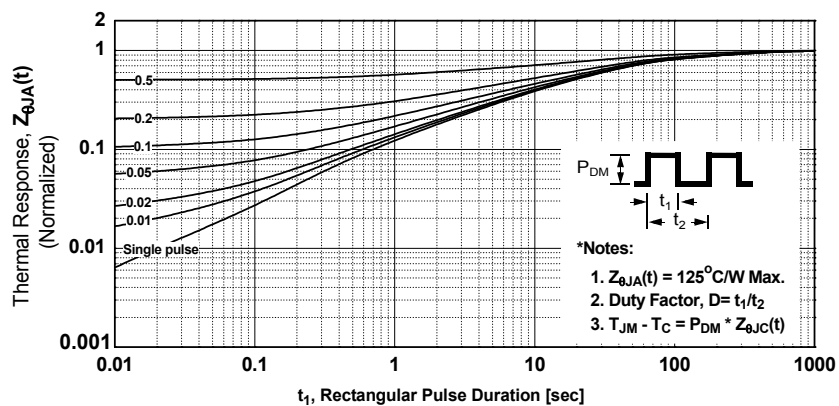


Figure 14. Gate Charge Test Circuit & Waveform

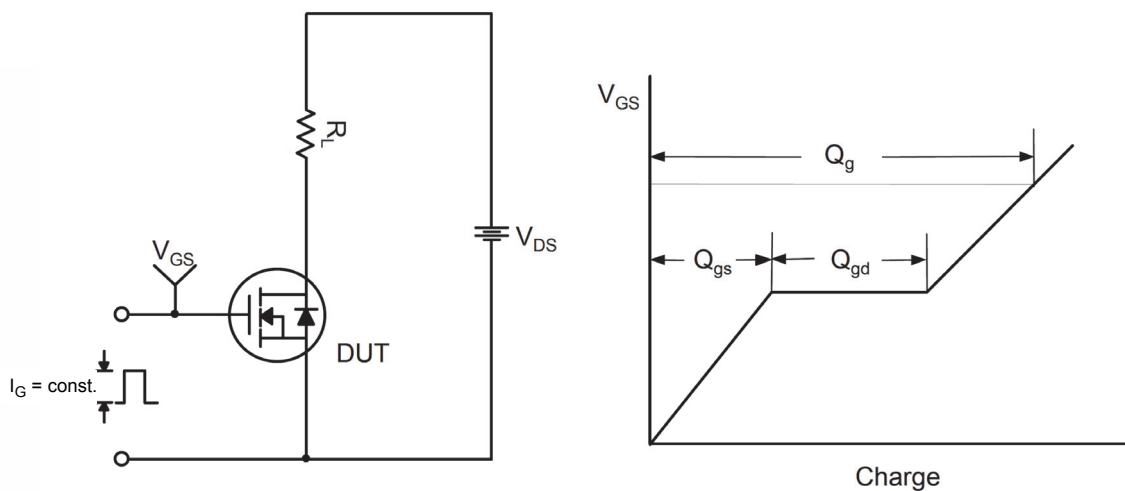


Figure 15. Resistive Switching Test Circuit & Waveforms

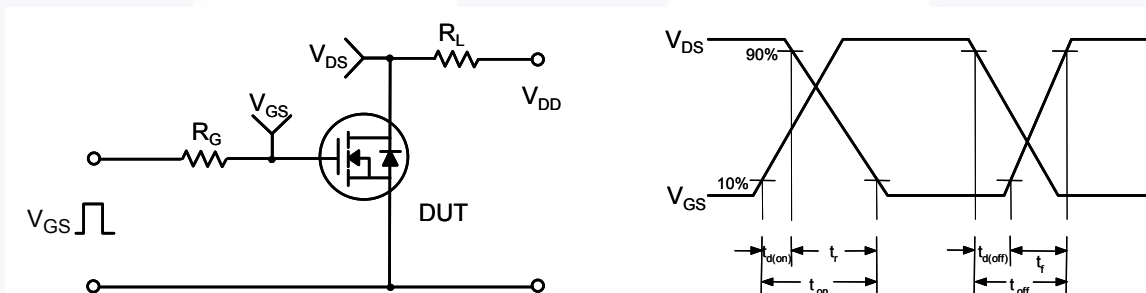
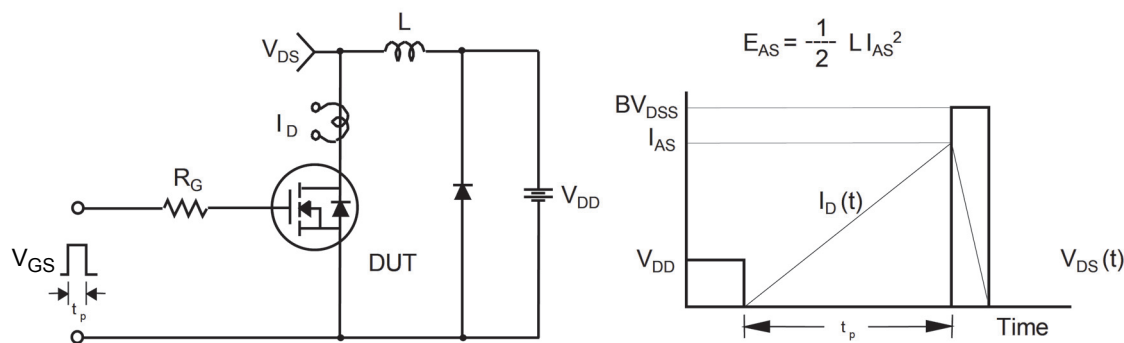


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms



### Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

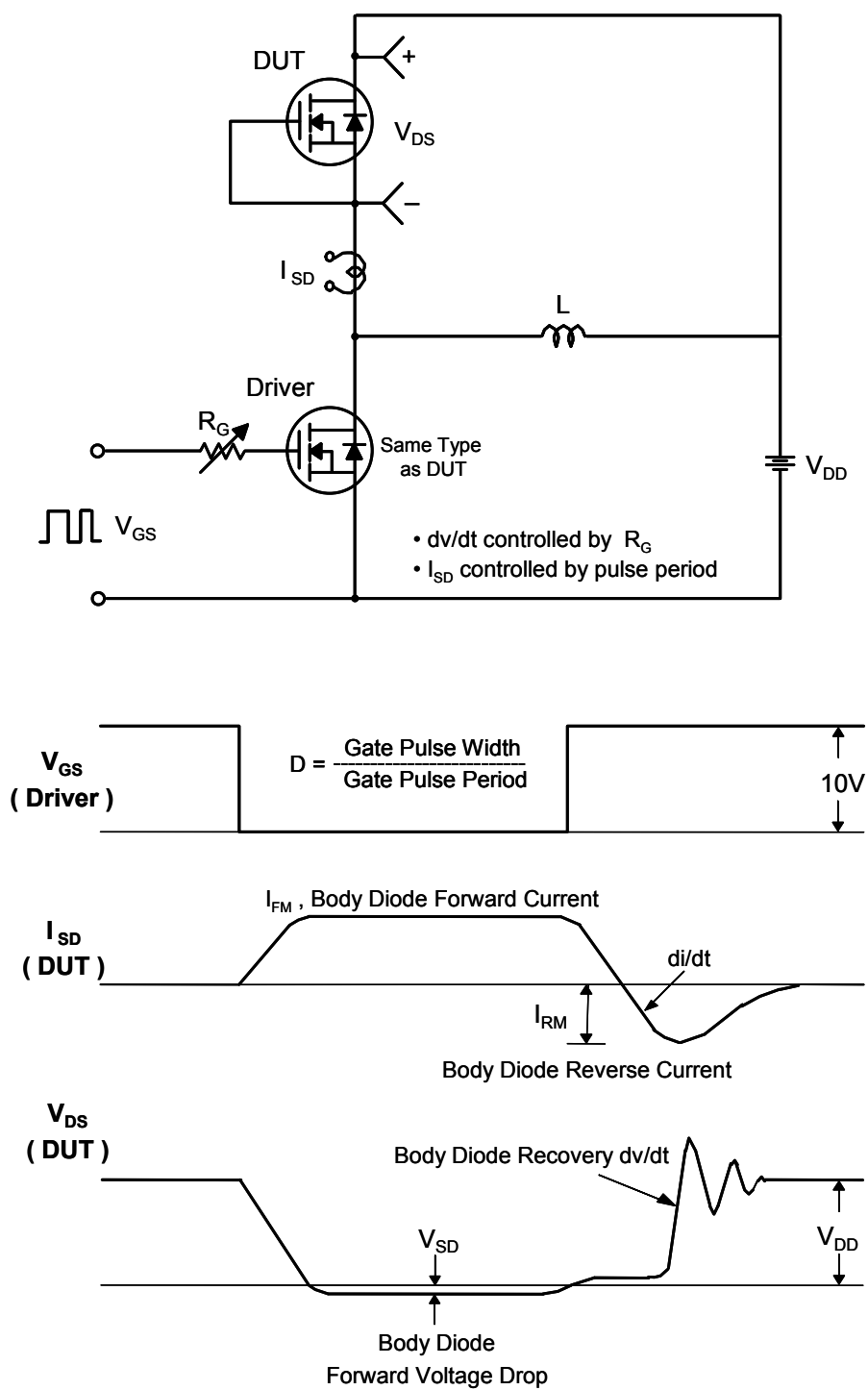
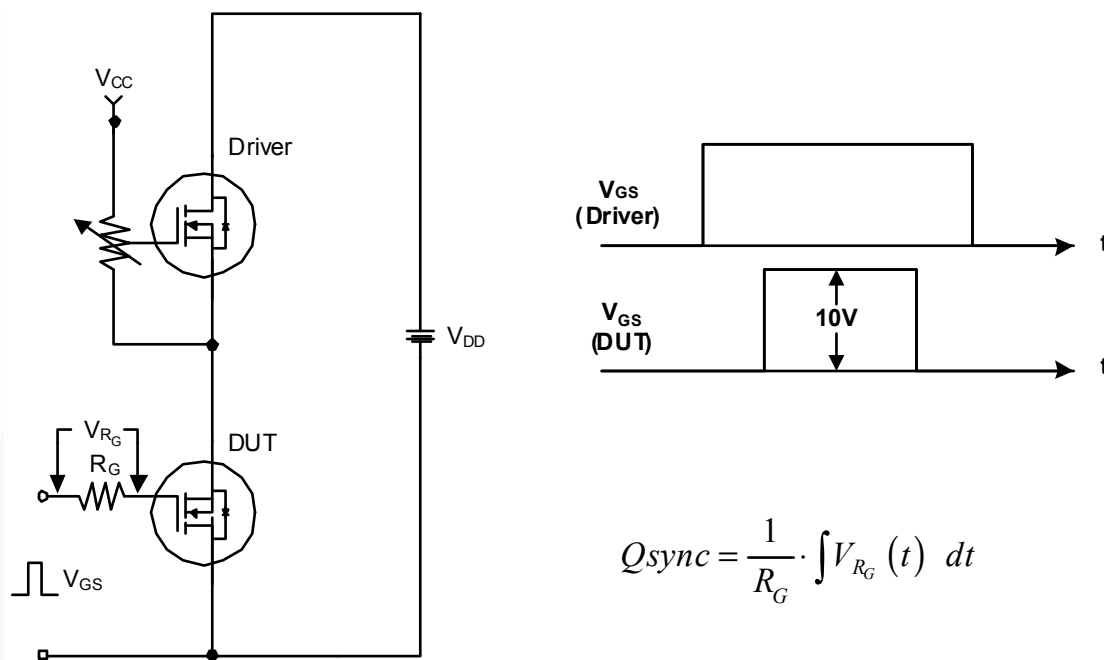
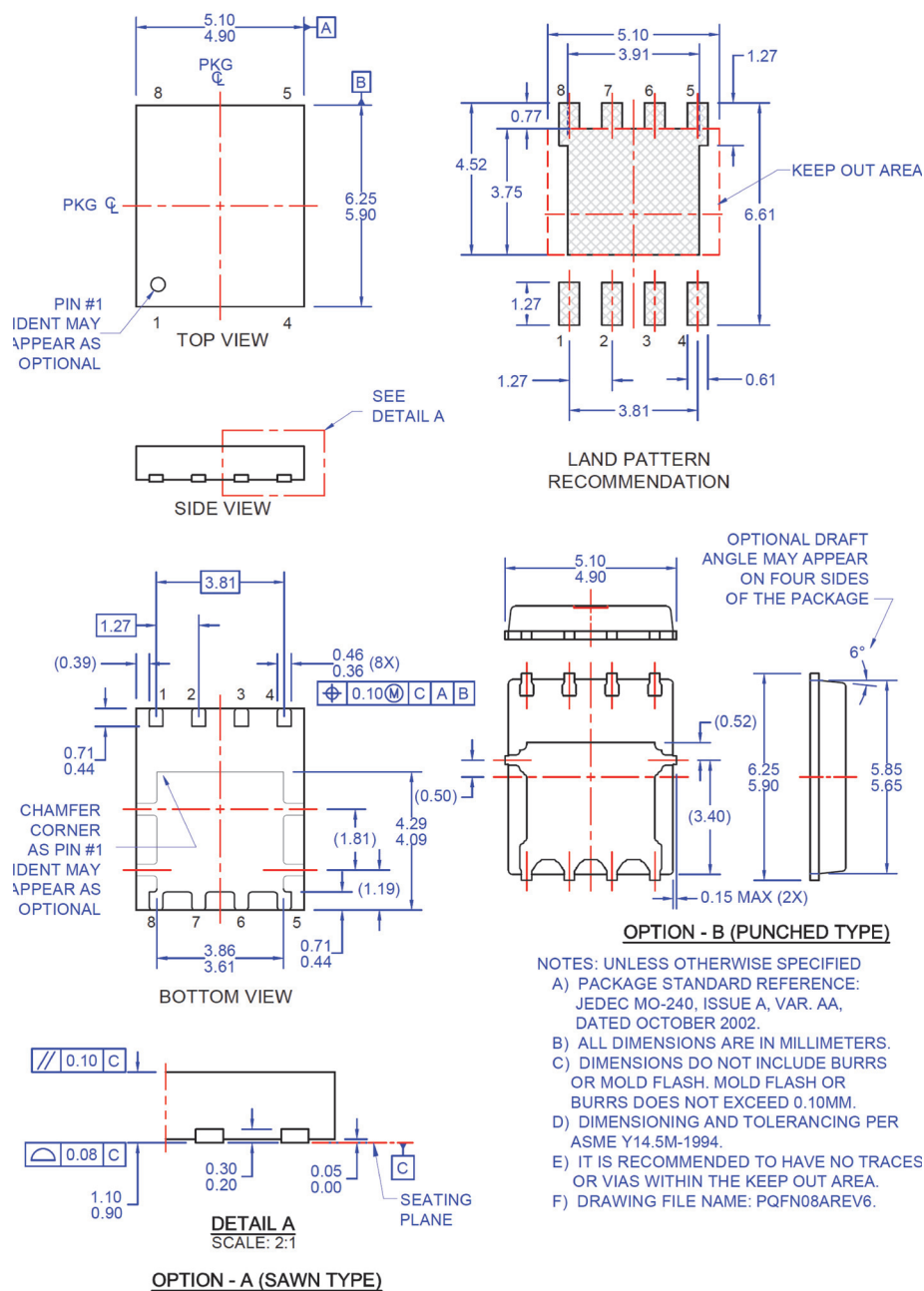


Figure 18. Total Gate Charge  $Q_{sync}$ . Test Circuit & Waveforms



## Mechanical Dimensions



**Figure 19. 8LD, PQFN, JEDEC MO-240 AA, 5.0X6.0MM**

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Rev. I66

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